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MDOB42005CV-EWM 4 x 20			OLED Module					
	Specification							
Version: 1		Date: 18/04/2020						
	Revision							
1	16/04/2020	First Issue						

Displ	y Features		
Character Count	4 x 20		
Appearance	White on Black		
Logic Voltage	5V		1
Interface	Multi		ROHS ompliant
Font Set	Multi		omnliant
Character Height	4.77 mm		omphant
Module Size	92.00 x 31.50 x 7.00 mm		
Operating Temperature	-40°C ~ +80°C	Box Quantity	Weight / Display
Construction	COB		

* - For full design functionality, please use this specification in conjunction with the SSD1311 specification. (Provided Separately)

Display Accessories					
Part Number Description					

Optional Variants					
Appearance	Voltage				

General Specification

The Features is described as follow:

■ Module dimension: 92.0 x 31.5 x 7.0 Max. mm

View area: 72.42 x 22.82mmActive area: 70.42 x 20.82 mm

Number of Characters: 20 characters x 4 Lines

Dot size: 0.57 x 0.57 mmDot pitch: 0.60 x 0.60 mm

Character size: 2.97 x 4.77 mmCharacter pitch: 3.55 x 5.35 mm

■ Duty: 1/32

■ Emitting Color: OLED , White

■ IC: SSD1311

■ Interface: 6800,8080,SPI,I2C

■ Size: 2.89 inch

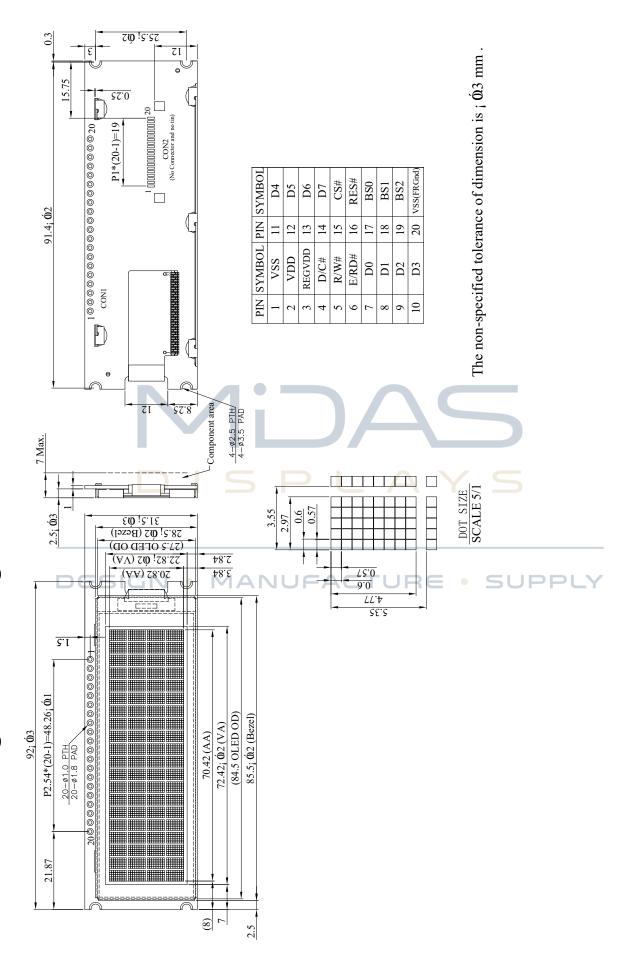
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Interface Pin Function

Pin No.	Symbol	Pin Type	Description
1	VSS	Р	Ground
2	VDD	Р	Power supply and power supply for interface logic level.
3	REGVDD	I	Internal VDD regulator selection pin in 5V I/O application mode. When this pin is pulled HIGH, internal VDD regulator is enabled (5V I/O application). When this pin is pulled LOW, internal VDD regulator is disabled (Low voltage I/O application).
4	D/C#	-	This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register. In I2C mode, this pin acts as SA0 for slave address selection. When serial interface is selected, this pin must be connected to VSS.
5 -	R/W# (WR#)) S	This pin is read / write control input pin connecting to the MCU interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
6	E/RD#	I	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.

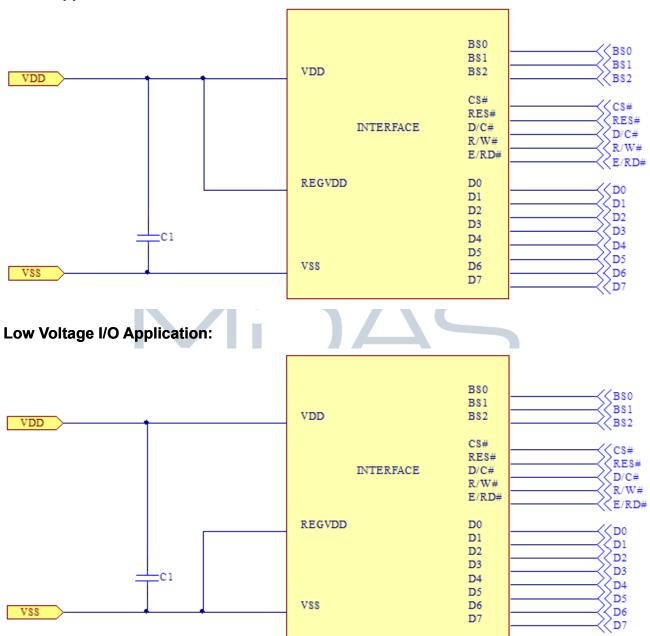
7	D0		These pins are bi-directional data bus connecting to the				
8	D1		MCU data bus.				
9	D2		Unused pins are recommended to tie LOW.				
10	D3		When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SID and D2 will be the serial data output: SOD.				
11	D4	I/O					
12	D5		·				
13	D6		When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the				
14	D7		serial clock input, SCL.				
15	CS#	ı	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW). In I2C mode, this pin must be connected to VSS.				
16	RES#	ı	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.				
17	BS0		setting as described in the following table. BS2, BS1 and BS0 are pin select. Bus Interface selection BS[2:0] Interface				
18	BS1	1	000 Serial Interface 001 Invalid 010 1 ² C 011 Invalid 100 8-bit 6800 parallel 101 4-bit 6800 parallel				
19	BS2	V • M	Note (1) 0 is connected to VSS (2) 1 is connected to VDD				
20	VSS (FRGnd)	Р	Ground				

Contour Drawing & Block Diagram



Application recommendations

5V I/O Application:



C1: 1.0uF

Note

The capacitor value is recommended value. Select appropriate value against module application

Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Notes
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TST	-40	+85	°C	-
Supply Voltage For Logic	VDD-VSS	-0.3	5.5	V	-

Electrical Characteristics

1. DC Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	VDD-VSS		4.8	5.0	5.3	V
Input High Volt.	VIH		0.8xVDD	Ŋ	VDD	V
Input Low Volt.	VIL	_	GND	_	0.2xVDD	V
Output High Volt.	VOH	IOH=-0.5mA	0.8xVDD	_	VDD	_ V
Output Low Volt.	MOLNU	IOL=0.5mA	GND	SU	0.2xVDD	V
50% Check Board Operating Current	IDD	VDD=5V	-	60	110	mA

Note: When you use 5V for Vdd please don't use 3V or 3.3V for logic I/O this will cause module does not work.

2. Initial code

WriteCmd(0x78);

void Initial_SSD1311(){ WriteCmd(0x08); //Display off WriteCmd(0x2A); //Function Set //RE = 1,SD = 0,IS = 0//Function Selection A WriteCmd(0x71); WriteData(0x4C); //Internal VDD Regulator ON for 5V I/O Application //WriteData(0x00); //Internal VDD Regulator OFF for Low Voltage I/O Application //Function Selection B WriteCmd(0x72); WriteData(0x00); //Select Font table WriteCmd(0x79); //OLED characterization ON //RE = 1,SD = 1,IS = 0//Set Contrast WriteCmd(0x81); WriteCmd(0xCF) WriteCmd(0xD5); //Set display clock divide Ratio WriteCmd(0x60); //105Hz DESIGN MANUFACTURE • SUPPLY WriteCmd(0xD9); //Set phase Length WriteCmd(0x78); WriteCmd(0xDA); //Set SEG pin Hardware Config. WriteCmd(0x10); //Default value WriteCmd(0xDB); //Set VcomH Deselect Level WriteCmd(0x40); WriteCmd(0xDC); // Function Selection C WriteCmd(0x03); // Internal VSL delay(10);

//OLED characterization

OFF

//RE = 1 ,SD=0,IS = 0

WriteCmd(0x09); // Extended function Set

WriteCmd(0x06); // scan direction

WriteCmd(0x28); //Function Set //Extended command Set ending

//RE = 0,SD=0,IS = 0

}

WriteCmd(0x01); //clear display

WriteCmd(0x02); //Return home

WriteCmd(0x06); //entry mode Set

WriteCmd(0x0C); //display on

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Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Anglo	(V)θ		160		_	deg
View Angle	(Η)φ	_	160	_	_	deg
Contrast Ratio	CR	Dark	2000:1	_	_	_
Deepered Time	T rise	_	_	10	_	μs
Response Time	T fall	_	_	10	_	μs
Display with 50% check Board Brightness		_	60	80	_	cd/m2
CIEx(Whi	(CIE1931)	0.26	0.28	0.30	_	
CIEy(Whi	(CIE1931)	0.30	0.32	0.34	_	



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Conditions

/ Initial 50% check board

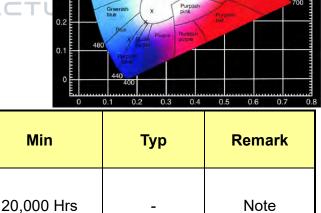
brightness Typical Value

OLED Lifetime

ITEM

Operating

Life Time



Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

Ta=25°C

Reliability

Content of Reliability Test

l Test	T	T
Content of Test	Test Condition	Applicable Standard
Endurance test applying the high storage temperature for a long time.	85°C 240hrs	
Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	
Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs)
Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	5
Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C /80°C 30 cycles	SUPPLY
st		
Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	
	Endurance test applying the low storage temperature for a long time. Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. Endurance test applying the electric stress under low temperature for a long time. Endurance test applying the high temperature and high humidity storage for a long time. Endurance test applying the high temperature and high humidity Operation for a long time. Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle St Endurance test applying the vibration during transportation and using.	Endurance test applying the high storage temperature for a long time. Endurance test applying the low storage temperature for a long time. Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. Endurance test applying the electric stress under low temperature for a long time. Endurance test applying the high temperature and high humidity storage for a long time. Endurance test applying the high temperature and high humidity Operation for a long time. Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30 cycles St Endurance test applying the vibration during transportation and using. Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z Endurance test applying the electric Air Discharge model

^{***} Supply voltage for OLED system =Operating voltage at 25°C

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels on/off exchange is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



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Inspection specification

Inspection Standard:

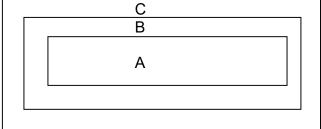
MIL-STD-105E table normal inspection single sample level II.

Definition

1 Major defect: The defect that greatly affect the usability of product.

2 Minor defect: The other defects, such as cosmetic defects, etc.

Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

Inspection Methods

1 The general inspection: Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.

2 The luminance and color coordinate inspection: By SR-3 or BM-7 or the equal equipments, in the dark room, under 25±5°C.

NO	Item	Criterion	AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 	0.65
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 	2.5

NO	Item	Criterion	AQL		
	OLED black spots, white spots, contamin ation (non-display)	3.1 Round type : As following drawing $\Phi=(x+y)/2$ $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5		
03		3.2 Line type : (As following drawing) Length Width Acceptable Q TY W≤0.02 ignore A+B L≤3.0 0.02 <w≤0.03 0.03<w≤0.05="" 0.05<w="" as="" l≤2.5="" round="" td="" type<=""><td>2.5</td></w≤0.03>	2.5		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	2.5		
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination.			

NO	Item	Criterion	
	Chipped	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels: z: Chip thickness y: Chip width x: Chip length	2.5
		$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	
	glass	⊙ If there are 2 or more chips, x is total length of each chip.	
06		6.1.2 Corner crack: z: Chip thickness y: Chip width $Z \le 1/2t$ Not over viewing area $1/2t < z \le 2t$ Not exceed $1/3k$ $1/2t < z \le 2t$ Not exceed $1/3k$ $1/8a$ Olf there are 2 or more chips, x is the total length of each chip.	2.5
	Glass crack	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	

NO	Item	Criterion	
06	Glass crack	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	

NO	Item	Criterion	AQL
10	PCB, COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	2.5 0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than	2.5
		three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	2.5 0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation	2.5 2.5
		or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 0.65
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface	2.5
12		Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on	0.65 2.5
		product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5 2.5
		sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.12.8 Pin type must match type in specification sheet.	2.5 0.65
		12.9 OLED pin loose or missing pins.12.10 Product packaging must the same as specified on packaging specification sheet.	0.65 0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

Check Item	Classification	Criteria	
No Display	Major		
Missing Line	Major		
Pixel Short	Major		
Darker Short	M ajor		
Wrong Display	ANUMajorCTU		
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Mormal B Dank Furel C Ellight Fixel	

Precautions in use of OLED Modules

Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Midas has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)
- (10) Midas has the right to upgrade or modify the product function.

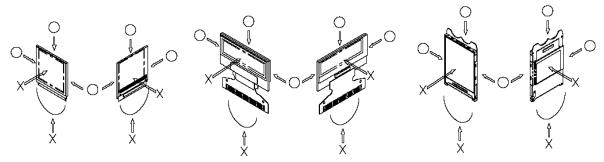
1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
 - * Pins and electrodes
 - * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

2. Storage Precautions

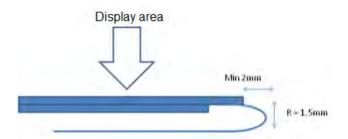
- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Midas. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

3. Designing Precautions

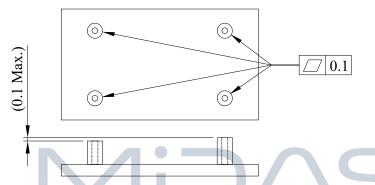
- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
 - * Connection (contact) to any other potential than the above may lead to rupture of the IC.
- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same

image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.

(11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



(13) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.



4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

